Listing of Claims:

1-20. (canceled)

21. A method of fabricating a packaged semiconductor chip, comprising:

bonding a wire on a chip contact pad of a semiconductor chip using a wire bonding machine;

moving a bond head of the wire bonding machine relative to the chip contact pad, thereby pulling a first length of the wire out of the wire bonding machine, wherein part of the wire passes through a space between a first outer edge of a first bearing race and a second outer edge of a second bearing race during the pulling of the first length;

bonding the wire on a lead using the wire bonding machine;

energizing a first piezoelectric element in the bond head, thereby causing the first piezoelectric element to expand and press against the first bearing race;

braking the first bearing race by the pressing of the first piezoelectric element against the first bearing race;

braking the wire between the first and second races at least partially by the braking of the first bearing race;

moving the bond head relative to the lead during the braking of the wire;

severing the wire proximate to the lead.

22. The method of claim 21, further comprising:

de-energizing the first piezoelectric element, thereby causing the first piezoelectric element to reduce in size, thereby ending the pressing of the first piezoelectric element against the first bearing race, and thereby causing a first tolerance gap to form between the first piezoelectric element and the first bearing race, such that the first bearing race may rotate with movement of the wire.

23. The method of claim 21, wherein the first bearing race rotates when the wire part passes through the space between the first outer edge of the first bearing race and the second outer edge of the second bearing race during the pulling of the first length of the wire.

24-25. (canceled)